

Publikationen

D. Stoichescu, Leon Binder, I. Tache, P. M. Svasta, Monica I. Ciolacu (2020): Education 4.0 - Jump to Innovation IoT in Higher Education. In: Proceedings of the 2019 IEEE 25th International Symposium for Design and Technology in Electronic Packaging (SIITME) [Oct 23-26, 2019; Cluj-Napoca, Romania], New York, NY, USA. DOI: 10.1109/SIITME47687.2019.8990825.